

1 Characteristics

Table 2. Absolute maximum ratings (limiting values)

Symbol	Parameter		Value	Unit	
$I_{T(RMS)}$	On-state rms current (180° conduction angle)		$T_c = 85\text{ °C}$	25	A
I_{TSM}	Non repetitive surge peak on-state current	$t_p = 2.5\text{ ms}$	$T_j = 25\text{ °C}$	390	A
		$t_p = 8.3\text{ ms}$		250	
		$t_p = 10\text{ ms}$		230	
I^2t	I^2t value for fusing	$t_p = 10\text{ ms}$	$T_j = 25\text{ °C}$	265	A^2s
di/dt	Critical rate of rise of on-state current $I_G = 500\text{ mA}$, $di_G/dt = 1\text{ A}/\mu s$	$F = 50\text{ Hz}$		100	$A/\mu s$
V_{DRM} V_{RRM}	Repetitive peak off-state voltage	TPDV825	$T_j = 125\text{ °C}$	800	V
		TPDV1025		1000	
		TPDV1225		1200	
T_{stg} T_j	Storage junction temperature range Operating junction temperature range			- 40 to + 150 - 40 to + 125	$^{\circ}C$
$V_{INS(RMS)}^{(1)}$	Insulation rms voltage			2500	V

1. A1, A2, gate terminals to case for 1 minute

Table 3. Electrical Characteristics ($T_j = 25\text{ °C}$, unless otherwise specified)

Symbol	Test conditions		Quadrant		Value	Unit
I_{GT}	$V_D = 12\text{ V DC}$, $R_L = 33\ \Omega$		I - II - III	MAX.	150	mA
V_{GT}				MAX.	1.5	V
V_{GD}	$V_D = V_{DRM}$ $R_L = 3.3\text{ k}\Omega$	$T_j = 125\text{ °C}$	I - II - III	MIN.	0.2	V
t_{gt}	$V_D = V_{DRM}$ $I_G = 500\text{ mA}$ $di_G/dt = 3\text{ A}/\mu s$		I - II - III	TYP.	2.5	μs
$I_H^{(1)}$	$I_T = 500\text{ mA}$ Gate open			TYP.	50	mA
I_L	$I_G = 1.2 \times I_{GT}$		I - III	TYP.	100	mA
			II		200	
dV/dt	Linear slope up to: $V_D = 67\% V_{DRM}$ Gate open	$T_j = 125\text{ °C}$		MIN.	2000	$V/\mu s$
$V_{TM}^{(1)}$	$I_{TM} = 35\text{ A}$ $t_p = 380\ \mu s$			MAX.	1.8	V
$V_{to}^{(1)}$	Threshold voltage			MAX.	1.1	V
$R_d^{(1)}$	Dynamic resistance			MAX.	19	$m\Omega$
I_{DRM} I_{RRM}	$V_{DRM} = V_{RRM}$	$T_j = 25\text{ °C}$		MAX.	20	μA
		$T_j = 125\text{ °C}$			8	mA
$(di/dt)_c^{(1)}$	$(dV/dt)_c = 200\text{ V}/\mu s$			MIN.	20	A/ms
	$(dV/dt)_c = 10\text{ V}/\mu s$				88	

1. For either polarity of electrode A_2 voltage with reference to electrode A_1 .

Table 4. Gate characteristics (maximum values)

Symbol	Parameter	Value	Unit
$P_{G(AV)}$	Average gate power dissipation	1	W
P_{GM}	Peak gate power dissipation	$t_p = 20 \mu s$ 40	W
I_{GM}	Peak gate current	$t_p = 20 \mu s$ 8	A
V_{GM}	Peak positive gate voltage	$t_p = 20 \mu s$ 16	V

Table 5. Thermal resistance

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction to ambient	50	$^{\circ}C/W$
$R_{th(j-c) DC}$	Junction to case for DC	1.5	$^{\circ}C/W$
$R_{th(j-c) AC}$	Junction to case for 360 $^{\circ}$ Conduction angle ($F = 50 Hz$)	1.1	$^{\circ}C/W$

Figure 1. Max. rms power dissipation versus on-state rms current ($F = 50Hz$). (curves limited by $(di/dt)_c$)

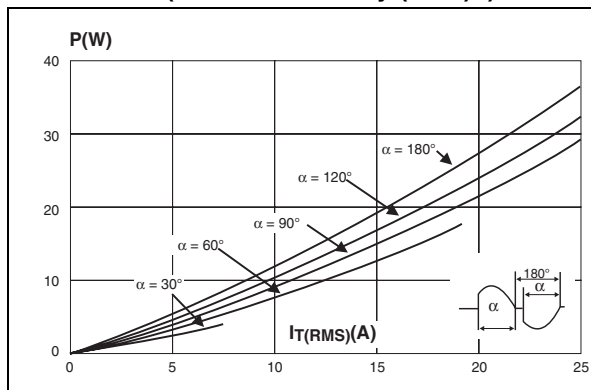


Figure 2. Max. rms power dissipation and max. allowable temperatures (T_{amb} and T_{case}) for various R_{th}

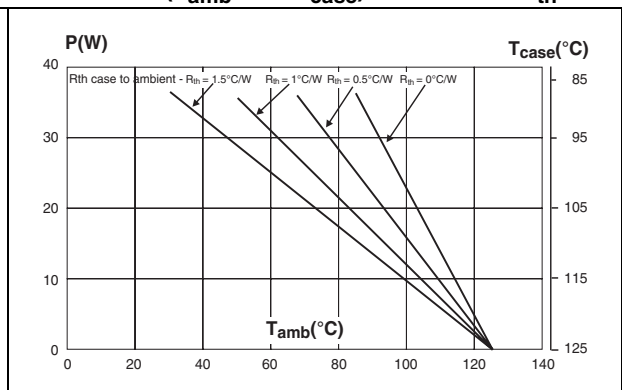


Figure 3. On-state rms current versus case temperature

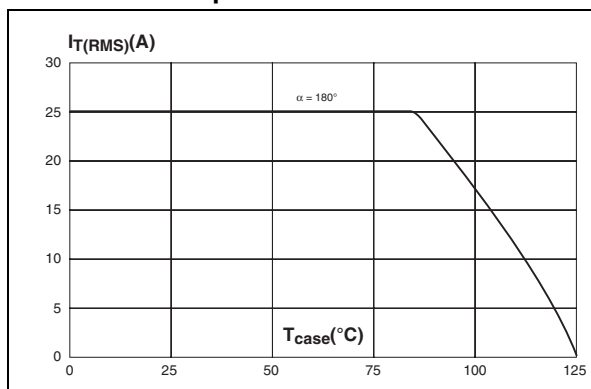


Figure 4. Relative variation of thermal impedance versus pulse duration

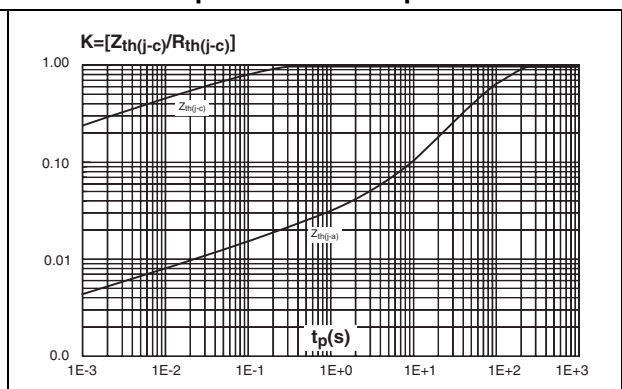


Figure 5. Relative variation of gate trigger current and holding current versus junction temperature

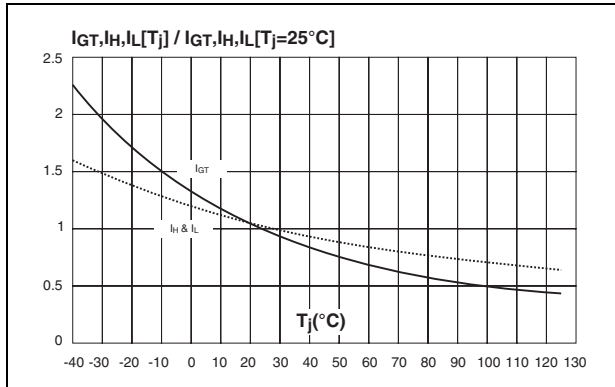


Figure 6. Non repetitive surge peak on-state current versus number of cycles

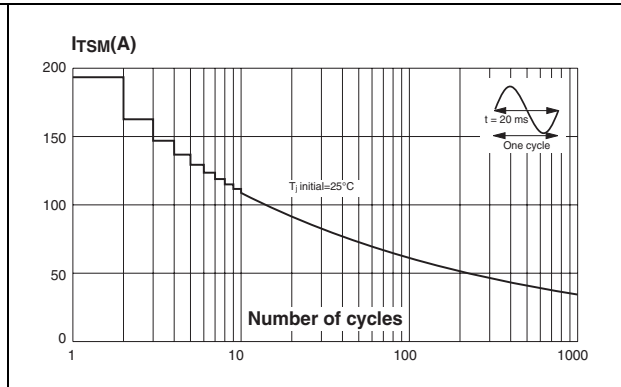


Figure 7. Non-repetitive surge peak on-state current for a sinusoidal pulse and corresponding values of I^2t

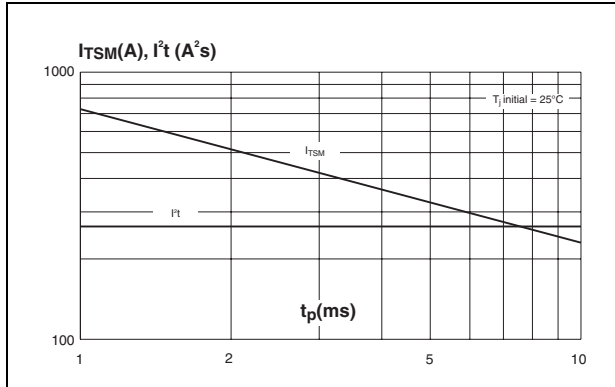


Figure 8. On-state characteristics (maximum values)

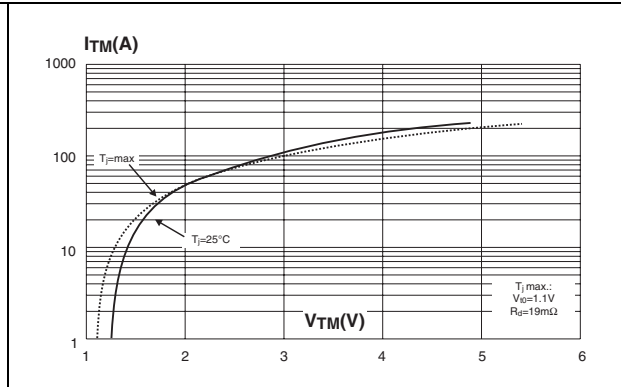
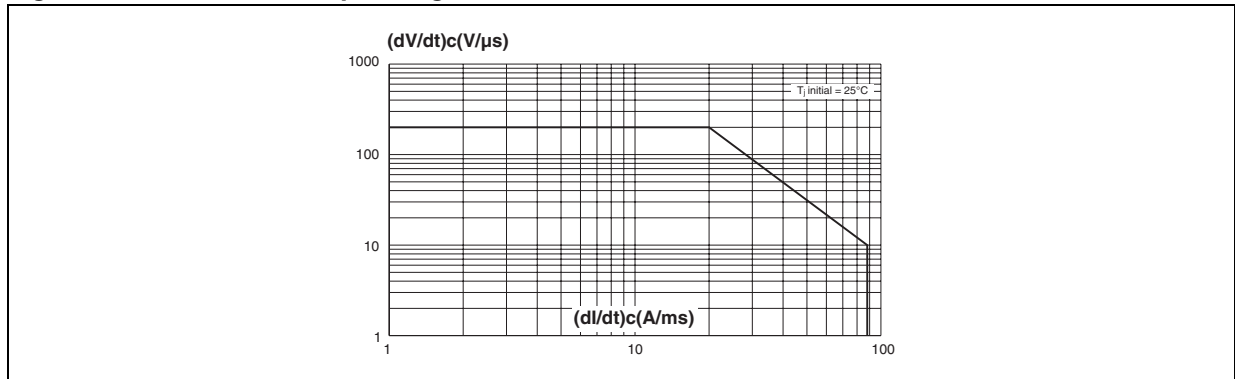


Figure 9. Safe turn-off operating area



2 Package information

- Epoxy meets UL94,V0
- Cooling method: C (by conduction)
- Recommended torque value: 0.9 to 1.2 N·m

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Table 6. TOP3 insulated dimensions

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	1.45	1.55	0.057	0.061
C	14.35	15.60	0.565	0.614
D	0.5	0.7	0.020	0.028
E	2.7	2.9	0.106	0.114
F	15.8	16.5	0.622	0.650
G	20.4	21.1	0.815	0.831
H	15.1	15.5	0.594	0.610
J	5.4	5.65	0.213	0.222
K	3.4	3.65	0.134	0.144
ØL	4.08	4.17	0.161	0.164
P	1.20	1.40	0.047	0.055
R	4.60 typ.		0.181 typ.	

3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
TPDV825RG	TPDV825	TOP3 insulated	4.5 g	30	Tube
TPDV1025RG	TPDV1025				
TPDV1225RG	TPDV1225				

4 Revision history

Table 8. Document revision history

Date	Revision	Changes
30-Mar-2011	1	First issue.
13-Jan-2012	2	Updated dI/dt in Table 2 and added V_{t0} and R_d to Table 3 .

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